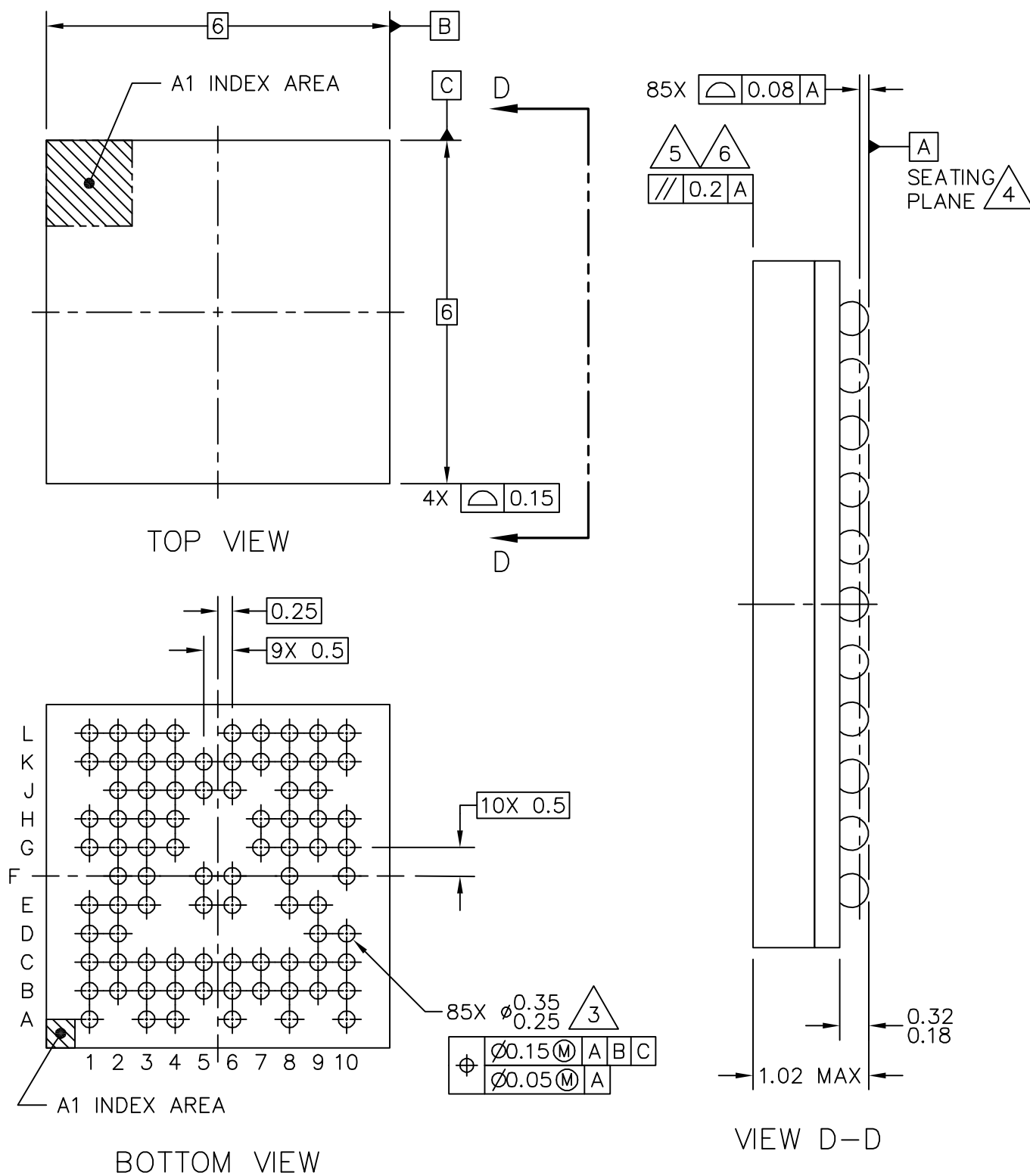




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TITLE: RCPBGA, 6 X 6 X 0.95 PKG, 0.5 MM PITCH, 85 I/O		DOCUMENT NO: 98ASA00540D	REV: C
		STANDARD: JEDEC MO-275 AACE-2	
		SOT1683-1	13 JAN 2016



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

6. SCORING OR GROOVES ON TOP SURFACE OF PACKAGE IS NOT PERMITTED.

7. NO VOIDS IN ENCAPSULATION PERMITTED.

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